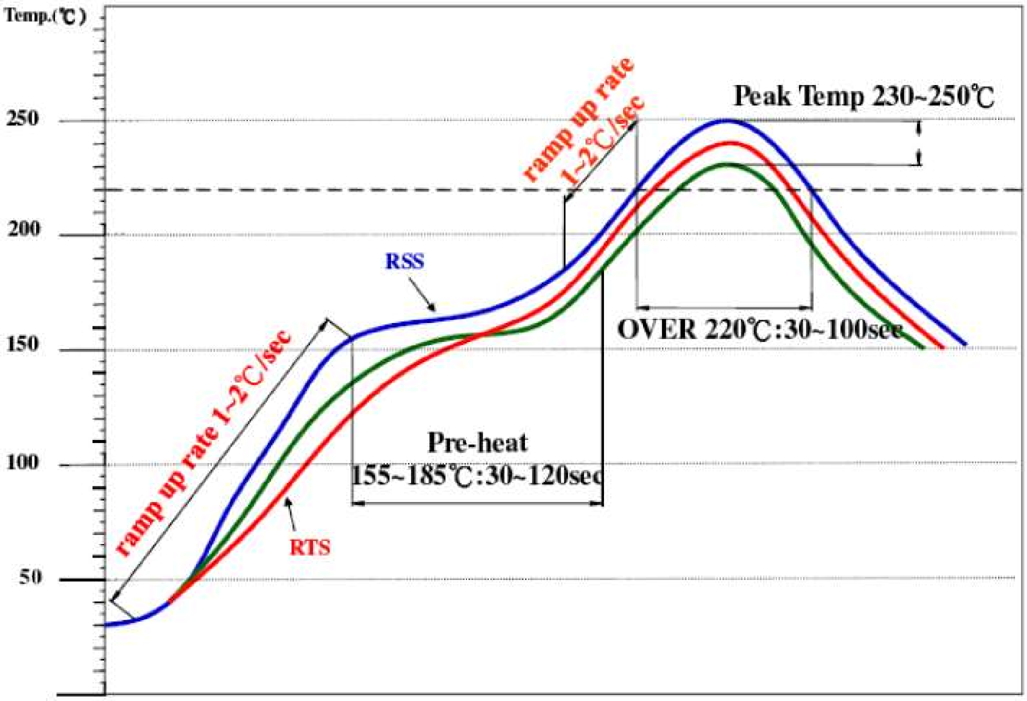
HF 212 Solder Paste Profile



ramp up rate(30~150 ℃) :	1.0~2.0 ℃/sec
pre-heating time(155~185 ℃) :	30~120 sec
time period above 220 ℃ :	30~100 sec
ramp up rate during reflow:	1.0~2.0 ℃/sec
peak temperature:	230~250 ℃
ramp down rate during cooling:	1.0~6.0 ℃/sec